

so that it makes possible to increase a signal transmission speed, whereby it can be intended to speed up an operation speed of a device.

(3) Due to the advantageous effects described in the above Items (1) and (2), since a signal transmission speed in an electronic
5 device can be increased, speeding up of an operation speed for the device is attained.

It will be appreciated by those of ordinary skill in the art that the present invention can be embodied in other specific forms without departing from the spirit or essential characteristics
10 thereof.

The presently disclosed embodiments are therefore considered in all respects to be illustrative and not restrictive. The scope of the invention is indicated by the appended claims rather than the foregoing description, and all changes that come within the
15 meaning and range of equivalents thereof are intended to be embraced therein.

WHAT IS CLAIMED IS:

1. A wiring board, comprising:

a predetermined wiring section being disposed on an
20 insulation board; and

an electromagnetic shielding film being placed at a position close to said wiring section.

2. The wiring board as claimed in claim 1, wherein conditions for disposing said wiring section as well as for said
25 electromagnetic shielding film, a condition for physical properties required for said electromagnetic shielding film, and a condition for frequency to be applied being selected so as to decrease an inductance of said wiring section as well as of inductive cross

talk.

3. A semiconductor device, comprising:

an electromagnetic shielding film being disposed on a surface,
on which an integrated circuit of a semiconductor chip has been
5 formed, through an insulating film;

a lead is provided on said electromagnetic shielding film
through an insulating film;

said lead is electrically connected to an external terminal
of said semiconductor chip; and

10 the resulting structured material being sealed with a sealing
material.

4. An electronic device, comprising:

the wiring board as claimed in claim 1; and

the semiconductor device as claimed in claim 3 which is to
15 be mounted on said wiring board.

5. A circuit board for electronic parts, comprising:

a circuit board prepared by forming a plurality of leads on
an insulating material; and

a conductor disposed on said plurality of leads through an
20 insulating material and reducing a self inductance of said plurality
of leads by flowing an eddy current through said conductor.

6. The circuit board for electronic parts as claimed in claim
5, wherein said insulation board being formed on a ground layer
decreasing a self inductance of said plurality of leads by flowing
25 said eddy current through said conductor; and

said conductor forming a composite sheet together with said
insulating material.

7. The circuit board for electronic parts as claimed in claim

6, wherein said insulating material contains an adhesive layer on the opposite side of said conductor.

8. The circuit board for electronic parts as claimed in claim 7, wherein a total thickness of said insulating material and said
5 adhesive layer is from 10 to 100 μ m.

9. The circuit board for electronic parts as claimed in claim 5, wherein said conductor is a foil having a thickness of at least 10 μ m.